

In Th Specification

At page 1 before the "Technical Field" section, please insert the following:

--RELATED PATENT DATA

A2 This patent resulted from a divisional application of U.S. Patent Application Serial No. 09/449,025, filed November 24, 1999, entitled "Physical Vapor Deposition Targets, Conductive Integrated Circuit Metal Alloy Interconnects, Electroplating Anodes, and Metal Alloys For Use as a Conductive Interconnection in an Integrated Circuit", naming Shozo Nagano, Hinrich Hargarter, Jianxing Li and Jane Buehler as inventors, the disclosure of which is incorporated by reference.--

In the Claims

Cancel claims 1-30 and 34-59 without prejudice.

RECEIVED